

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of the claims in the application:

**Listing of Claims:**

Claims 1 – 16 (cancelled):

Claim 17 (currently amended): A multi-layer printed circuit board having at least one prefabricated integrated electronic component embedded therein comprising:

a circuit board substrate comprising the core of said multi-layer printed circuit board and having a first substrate surface and a second substrate surface;

a first integrated electronic component, where said first integrated electronic component is ~~[[a]]~~ prefabricated prior to being secured in a cavity in said first substrate surface ~~component~~;

an adhesive securing said first prefabricated integrated electronic component within and said first substrate surface cavity;

a first dielectric layer disposed on said first substrate surface and over said first integrated electronic component;

a metallic layer disposed on said first dielectric layer;

~~at least one~~ an electrically conductive first via passing through said first dielectric layer ~~and having a metal lining~~ in contact with said metallic layer; and

a second dielectric layer disposed over said first via and over said metallic layer, ~~said first dielectric layer and said second dielectric layer having a~~ second electrically conductive via structure defining at least one opening exposing at least part of extending through said first and second dielectric layers and electrically coupled to said first integrated electronic component, ~~said opening supporting an opening metal lining which is coupled to said first integrated electronic component.~~

Claim 18 (previously presented): The multi-layer printed circuit board of Claim 17 additionally comprising a first metallic layer disposed on said first substrate surface and a second metallic layer disposed on said second substrate surface.

Claim 19 (original): The multilayer printed circuit board of Claim 17 wherein said circuit board substrate comprises a multi-layer core substrate.

Claim 20 (currently amended): The multilayer printed circuit board of Claim 17 wherein said ~~at least one first~~ via ~~passes~~ extends from said first substrate surface to said second substrate surface.

Claim 21 (currently amended): The multilayer printed circuit board of Claim 18 wherein said ~~at least one first~~ via ~~passes~~ extends from said first substrate surface to said second substrate surface.

Claim 22 (currently amended): The multilayer printed circuit board of Claim 18 wherein said first metallic layer ~~comprises a~~ is patterned ~~first metallic layer~~ to expose at least a portion of said first substrate surface, and said first prefabricated integrated electronic component ~~being~~ is secured within said cavity in ~~to~~ said exposed portion of said first substrate surface.

Claim 23 (currently amended): The multilayer printed circuit board of Claim 18 wherein said second metallic layer ~~comprises a~~ is patterned ~~second metallic layer~~ to expose at least a portion of said second substrate surface.

Claim 24 (original): The multilayer printed circuit board of Claim 23 additionally comprising a second integrated electronic component secured to said exposed portion of said second substrate surface.

Claim 25 (original): The multilayer printed circuit board of Claim 23 wherein said exposed portion of said second substrate surface includes a cavity.

Claim 26 (original): The multilayer printed circuit board of Claim 25 additionally comprising a second integrated electronic component disposed in said cavity.

Claim 27 (currently amended): The multilayer printed circuit board of Claim 17 ~~additionally comprising at least one first pad disposed on~~ wherein said first prefabricated integrated electronic component ~~and~~ comprises a conductive pad contacting said metallic layer.

Claim 28 (currently amended): The multilayer printed circuit board of Claim 25 additionally comprising ~~at least one first pad disposed on~~ wherein said first prefabricated integrated electronic component ~~and~~ comprises a conductive pad contacting said metallic layer.

Claim 29 (currently amended): The multilayer printed circuit board of Claim 26 additionally comprising ~~at least one first pad disposed on~~ wherein said first prefabricated integrated electronic component ~~and~~ comprises a conductive pad contacting said metallic layer.

Claim 30 (original): The multilayer printed circuit board of Claim 17 additionally comprising at least one metal-lined via extending through said metallic layer and through said first dielectric layer.

Claim 31 (original): The multilayer printed circuit board of Claim 25 additionally comprising at least one metal-lined via extending through said metallic layer and through said first dielectric layer.

Claim 32 (original): The multilayer printed circuit board of Claim 26 additionally comprising at least one metal-lined via extending through said metallic layer and through said first dielectric layer.

Claim 33 (original): The multilayer printed circuit board of Claim 27 additionally comprising at least one metal-lined via extending through said metallic layer and through said first dielectric layer.

Appl. No. 09/886,092  
Amendment "C"

Claim 34 (original): The multilayer printed circuit board of Claim 33 additionally comprising a patterned metal layer disposed on said second dielectric layer.

Claim 35 (cancelled.)